

Product Change Notice (PCN)

Subject: Alternate wafer Front Side Metallization (FSM) and Back Grinding Back Metallization (BGBM) facility of the listed Renesas PQFN packaged products

Publication Date: 10/30/2025

Effective Date: 1/28/2026

Revision Description:

Initial Release

Description of Change:

Alternate wafer FSM and BGBM facility of the listed Renesas PQFN packaged products
 - LB Semi Co., Ltd. (formerly LB Lusem Co., Ltd.), Gumi-si, Republic of Korea

Affected Devices:

ISL99360FRZ-T	ISL99390FRZ-TR5935	RAA2213204S05GNP#HBO	RAA2214544GNP#HBO	RAA2214914S0DGNP#HBO
ISL99360FRZ-TR6071	ISL99390FRZ-TR5948	RAA2213204S09GNP#HBO	RAA2214904GNP#HBO	RAA2214934GNP#HBO
ISL99360FRZ-TS2568	ISL99390FRZ-TR5953	RAA2213404GNP#HBO	RAA2214904GNP#HBA	RAA2214944GNP#HBO
ISL99360FRZ-TS2696	ISL99390FRZ-TR5992	RAA2213404R1YGNP#HBO	RAA2214904GNP#HBB	RAA2214974GNP#HBO
ISL99360FRZ-TS2795	ISL99390FRZ-TR6071	RAA2213404R60GNP#HBO	RAA2214904S05GNP#HBO	RAA2214974GNP#HBA
ISL99360HRZ-T	ISL99390FRZ-TR6074	RAA2213404S02GNP#HBO	RAA2214904S09GNP#HBO	RAA2214974S02GNP#HBA
ISL99360HRZ-TS2709	ISL99390FRZ-TR6079	RAA2213404S05GNP#HBO	RAA2214904S0DGNP#HBO	RAA2257034GNP#HBO
ISL99380FRZ-TR5935	ISL99390FRZ-TS2773	RAA2213404S09GNP#HBO	RAA2214914GNP#HBO	< Blank >
ISL99380FRZ-TR5953	RAA2213204GNP#HBO	RAA2214504GNP#HBO	RAA2214914R60GNP#HBO	< Blank >
ISL99380FRZ-TR6071	RAA2213204R60GNP#HBO	RAA2214504R6AGNP#HBO	RAA2214914S02GNP#HBO	< Blank >
ISL99380FRZ-TS2773	RAA2213204S02GNP#HBO	RAA2214504S02GNP#HBO	RAA2214914S06GNP#HBO	< Blank >

This notice is to inform you that Renesas Electronics America will begin using LB Semi, Republic of Korea as alternate wafer Front Side Metallization (FSM) and Back Grinding Back Metallization (BGBM) facility for the products listed above, which will be assembled into Renesas PQFN (Power Quad Flat No-Leads) packaged products.

Reason for Change:

The LB Semi facility is ISO9001:2015 and IATF16949 certified. LB Semi facility is being added as alternate wafer FSM and BGBM facility to expand current capacity and optimize Renesas’s ability to meet customer’s delivery requirements for the listed devices above. There is no change to the use of existing wafer fabrication, assembly and test sites.

Impact on fit, form, function, quality & reliability:

The qualification plan is designed using JEDEC and other applicable industry standards to confirm there is no impact to form, fit, function or interchangeability of the product. A summary of the qualification result is included for reference. Please refer Appendix A. The remainder of the manufacturing operations (wafer fabrication, package level electrical test, etc) will continue to be processed to previously established manufacturing flow.

Product Identification:

There will be no change in the external marking of the packaged parts. Products affected by

this change are identifiable via Renesas Electronics America Inc. internal traceability system. All shipments with date-codes prior to 01/28/2026 will contain only existing wafer FSM and BGBM material, whereas, shipments with date-codes on or after 01/28/2026 may contain both existing and new (LB Semi) FSM and BGBM material.

Qualification status: Completed, See attached
Sample availability: subject to sample and material availability
Device material declaration: Available upon request

Customers may expect a minimum of 3 months for sample replenishment upon request.

Note:

1. Acknowledgement must be received by Renesas within 30 days or Renesas will consider the change as approved.
2. If timely acknowledgement is provided by Customer, then Customer shall have 90 days from the date of receipt of this PCN to make any objections to this PCN. If Customer fails to make objections to this PCN within 90 days of the receipt of the PCN then Renesas will consider the PCN changes as approved.
3. If customer cannot accept the PCN then customer must provide Renesas with a last time buy demand and purchase order.

For additional information regarding this notice, please contact your regional change coordinator (below)			
Americas: PCN-US@RENESAS.COM	Europe: PCN-EU@RENESAS.COM	Japan: PCN-JP@RENESAS.COM	Asia Pac: PCN-APAC@RENESAS.COM

Appendix A : Qualification result

Test Description	Condition	ISL99390BFRZ-TR5935 39 Leads, 5mm x 6mm x 0.75mm PQFN Package
High Temperature Operating Life (HTOL) +125°C	2000 hours	N=240 Acc = 0
Biased High Accelerated Stress Test (bHAST) +110°C ; 85% RH	264 hours	N=240 Acc = 0 L3 Pb-Free
Moisture Sensitivity Level	Level 3	N=742 Acc = 0 L3 Pb-Free
Unbiased Highly Accelerated Stress Test (uHAST) +130°C ; 85% RH	96 hours	N=240 Acc = 0 L3 Pb-Free
Temperature Cycle (TCT) -40°C / +125°C	1000 cycles	N=240 Acc = 0 L3 Pb-Free
Hot Temperature Storage (HTS) +150°C	2000 hours	N=240 Acc = 0

Pass Qualification